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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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May 2013

# FSA2257 Low R<sub>ON</sub>, Low-Voltage Dual SPDT Bi-Directional Analog Switch

#### **Features**

- Maximum 1.15 Ω On Resistance (R<sub>ON</sub>) at 4.5 V V<sub>CC</sub>
- 0.3 Ω Maximum R<sub>ON</sub> Flatness at +5 V V<sub>CC</sub>
- Space-Saving MicroPak™
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.50 V
- Fast Turn-On and Turn-Off Time
- Break-Before-Make Enable Circuitry
- Over-Voltage Tolerant TTL-Compatible Control Input

#### **Applications**

- Cell Phone
- PDA
- Mobile Devices

### **Description**

The FSA2257 is a high-performance bi-directional dual Single-Pole/Double-Throw (SPDT) analog switch. This switch can be configured as either a multiplexer or a demultiplexer by select pins. The device features ultra-low  $R_{ON}$  of 1.3  $\Omega$  maximum at 4.5 V  $V_{CC}$  and operates over the wide  $V_{CC}$  range of 1.65 V to 5.50 V. The device is fabricated with submicron CMOS technology to achieve fast switching speeds and is designed for break-beforemake operation. The select input is TTL-level compatible.

## **Ordering Information**

Part Number	Package Number	Top Mark	Package Description	Packing Method
FSA2257L10X	MAC10A	EP	10-Lead MicroPak™, 1.6 x 2.1 mm	5000 Units Tape and Reel
FSA2257MTCX	MCT14	FSA2257	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4 mm Wide	2500 Units Tape and Reel
FSA2257MUX	MUA10A	FSA 2257	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0 mm	4000 Units Tape and Reel

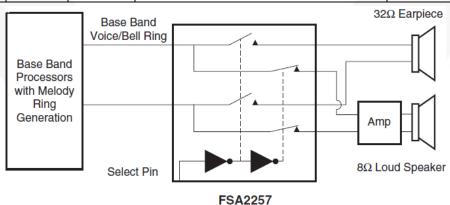
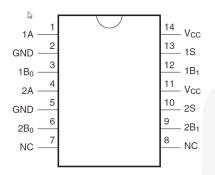


Figure 1. Block Diagram

## **Pin Configurations**



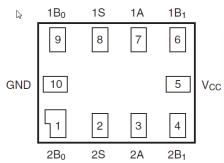
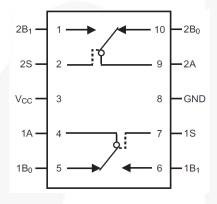


Figure 2. Pin Assignments for TSSOP (Top View)

Figure 3. MicroPak™ Pad Assignments (Top View)



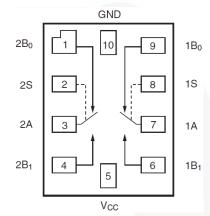


Figure 4. Pin Assignments for MSOP (Top View)

Figure 5. Analog Symbols (Top Through View)

#### **Pin Definitions**

Pin# TSSOP	Pin# MicroPak™	Pin # MSOP	Name	Description
1	7	4	1A	Data Ports
2,5	10	8	GND	Ground
3	9	5	1B <sub>0</sub>	Data Ports
4	3	9	2A	Data Ports
6	1	10	2B <sub>0</sub>	Data Ports
7,8			NC	No Connect
9	4	1	2B <sub>1</sub>	Data Ports
10	2	2	28	Control Inputs
11,14	5	3	Vcc	Power Supply
12	6	6	1B <sub>1</sub>	Data Ports
13	8	7	18	Control Inputs

#### **Truth Table**

Control Input (S)	Function
Low Logic Level	B₀ connected to A
High Logic Level	B <sub>1</sub> connected to A

#### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Paramet	ter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	Supply Voltage			
V <sub>SW</sub>	DC Switch Voltage <sup>(1)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
V <sub>IN</sub>	DC Input Voltage <sup>(1)</sup>		-0.5	6.0	V
	Input Diode Current		-50		
$I_{IK}$	Switch Current			200	mA
	Peak Switch Current (Pulsed at 1 ms	duration, <10% duty cycle)		400	
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
TJ	Maximum Junction Temperature			+150	°C
TL	Lead Temperature (Soldering, 10 sec	conds)		+260	°C
ESD	Flootrootatia Diacharga Canability	Human Body Model, JESD22-A114		8000	V
EOD	Electrostatic Discharge Capability	Charged Device Model, JESD22-C101		2000	V

#### Note:

1. Input and output negative ratings may be exceeded if input and output diode current ratings are observed.

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	1.65	5.50	V
$V_{CNTRL}$	Control Input Voltage <sup>(2)</sup>	0	V <sub>CC</sub>	V
$V_{SW}$	Switch Input Voltage	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

#### Note:

2. Unused control input must be held HIGH or LOW and it must not float.

#### **DC Electrical Characteristics**

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Conditions	Conditions V <sub>CC</sub> (V)		T <sub>A</sub> =+25°C		T <sub>A</sub> =-40 +85		Unit	
				Min.	Тур.	Max.	Min.			
			1.8 to 2.7				1.0			
$V_{IH}$	Input Voltage High		2.7 to 3.6				2.0		V	
			4.5 to 5.5				2.4			
			1.8 to 2.7					0.4		
$V_{IL}$	Input Voltage Low		2.7 to 3.6					0.6	V	
			4.5 to 5.5					0.8		
	Control Input	V 0.V/+- V/	2.7 to 3.6				-1.0	1.0		
I <sub>IN</sub>	Leakage	V <sub>IN</sub> =0 V to V <sub>CC</sub>	4.5 to 5.5				-1.0	1.0	μΑ	
I <sub>NO(OFF)</sub> , I <sub>NC(OFF)</sub>	Off Leakage Current of Port B <sub>0</sub> and B <sub>1</sub>	A=1 V, 4.5 V, B <sub>0</sub> or B <sub>1</sub> =1 V, 4.5 V	5.5	-2		2	-20	20	nA	
I <sub>A(ON)</sub>	On Leakage Current of Port A	A=1 V, 4.5V, B <sub>0</sub> or B <sub>1</sub> =1 V,4.5 V or Floating	5.5	-4		2	-40	40	nA	
	Switch On Resistance	I <sub>OUT</sub> =100 mA,	1.8		4.6					
		B <sub>0</sub> or B <sub>1</sub> =1.5 V	2.7		2.6	4.0		4.3		
R <sub>ON</sub>	MicroPak <sup>(3)</sup>	I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =3.5 V	4.5		0.95	1.15		1.30	Ω	
TON	Switch On Resistance	I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =1.5 V	2.7		2.8			4.5	32	
	MSOP/TSSOP <sup>(3)</sup>		I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>1</sub> =3.5 V	4.5		1.5	- 4		2.3	
ΔRon	On Resistance Matching Between Channels MicroPak (4)	I <sub>OUT</sub> =100 mA,	4.5		0.06	0.12		0.15	Ω	
ΔHQN	On Resistance Matching Between Channels MSOP / TSSOP <sup>(4)</sup>	B <sub>0</sub> or B <sub>1</sub> =3.5 V	4.5		0.7			0.3	2.2	
		I <sub>OUT</sub> =100 mA, B <sub>0</sub> or	1.8		3.0					
_	On Resistance	B <sub>I</sub> =0 V, 0.75 V,1.5 V	2.7		1.4					
R <sub>FLAT(ON)</sub>	Flatness <sup>(5)</sup>	I <sub>OUT</sub> =100 mA, B <sub>0</sub> or B <sub>I</sub> =0 V, 1 V, 2 V	4.5		0.2	0.3		0.4	Ω	
	Quiescent Supply	V <sub>IN</sub> =0 V or V <sub>CC</sub> ,	3.6		0.1	0.5		1.0	^	
I <sub>CC</sub>	Current	I <sub>OUT</sub> =0 V	5.5		0.1	0.5		0.4 0.6 0.8 1.0 1.0 20 40 4.3 1.30 4.5 2.3 0.15 0.4 1.0	μΑ	

- On resistance is determined by the voltage drop between A and B pins at the indicated current through the
- 4.  $\Delta R_{ON} = R_{ONmax} R_{ONmin}$  measured at identical  $V_{CC}$ , temperature, and voltage. 5. Flatness is defined as the difference between the maximum and minimum value of on resistance over the specified range of conditions.

## **AC Electrical Characteristics**

Typical values are at 25°C unless otherwise specified.

Symbol Parameter		Conditions	Conditions V <sub>cc</sub> (V)		T <sub>A</sub> =+25°C			T <sub>A</sub> =-40°C to +85°C		Figure
				Min.	Тур.	Max.	Min.	Max.		
		B <sub>0</sub> or B <sub>1</sub> =1.5 V,	1.8 to 2.7		75					
t <sub>ON</sub>	Turn-On	R <sub>L</sub> =50 $\Omega$ , C <sub>L</sub> =35 pF	2.7 to 3.6			50		60	ns	Figure 6
LOIV	Time	$B_0$ or $B_1$ =3.0 V, $R_L$ =50 $\Omega$ , $C_L$ =35 pF	4.5 to 5.5			35		40	ns ns pC dB dB MHz	i igaio o
		B <sub>0</sub> or B <sub>1</sub> =1.5 V,	1.8 to 2.7		20					Figure 6
toff	Turn-Off	$R_L=50 \Omega$ , $C_L=35 pF$	2.7 to 3.6			20		30	ns	
IOFF	Time	$B_0$ or $B_1$ =3.0 V, $R_L$ =50 $\Omega$ , $C_L$ =35 pF	4.5 to 5.5			15		20	110	i iguio o
. 7	Break-	$B_0$ or $B_1$ =1.5 V, $R_L$ =50 Ω, $C_L$ =35 pF	2.7 to 3.6				1		ns	Figure 7
t <sub>BBM</sub>	Before-Make Time	$B_0$ or $B_1$ =3.0 V, $R_L$ =50 Ω, $C_L$ =35 pF	4.5 to 5.5		20		1			
Q	Charge	C <sub>L</sub> =1.0 nF, V <sub>GEN</sub> =0 V,	2.7 to 3.6		20				20	Figure 9
Q	Injection	R <sub>GEN</sub> =0 Ω	4.5 to 5.5		10				δ	
OIRR	Off Isolation	f=1 MHz, R <sub>L</sub> =50 Ω	2.7 to 3.6		-70				٩D	Figure 8
Oinn	On isolation	1=1 WITZ, NL=30 \$2	4.5 to 5.5		-70				GD.	rigure o
			2.7 to 3.6		-75					
Xtalk	Crosstalk	f=1 MHz, $R_L$ =50 $\Omega$	4.5 to 5.5		-75				dВ	Figure 8
BW	-3 db	D 50 0	2.7 to 3.6		200				N 41 1-	Figure
BVV	Bandwidth	R <sub>L</sub> =50 Ω	4.5 to 5.5		200				IVIHZ	11
THD	Total Harmon	R <sub>L</sub> =600 Ω, V <sub>IN</sub> =0.5 V <sub>PP</sub>	2.7 to 3.6		0.002				%	Figure
1110	Distortion	f=20 Hz to 20 kHz	4.5 to 5.5		0.002				70	12

## Capacitance

Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	T <sub>A</sub> =+25°C		T <sub>A</sub> =+25°C Uni		Unit	Figure
				Min.	Тур.	Max.		$\mathbb{R}^{(1)}$	
C <sub>IN</sub>	Control Pin Input Capacitance	f=1 MHz	0		3.5		pF	Figure 10	
C <sub>OFF</sub>	B Port Off Capacitance	f=1 MHz	4.5		12.0		pF	Figure 10	
C <sub>ON</sub>	A Port On Capacitance	f=1 MHz	4.5		40.0		pF	Figure 10	

## **AC Loadings and Waveforms**

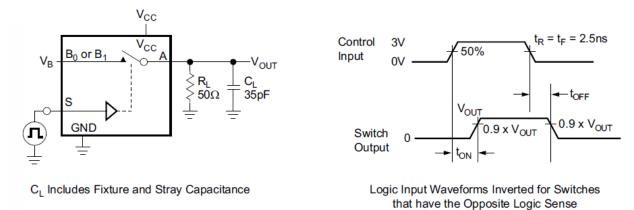
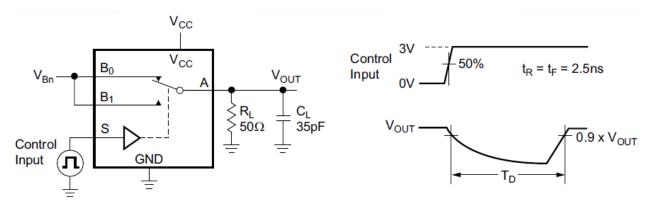


Figure 6. Turn On / Off Timing



C<sub>L</sub> Includes Fixture and Stray Capacitance

Figure 7. Break Before Make Timing

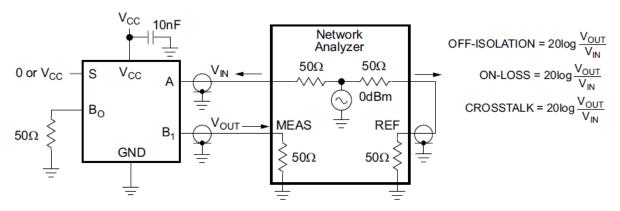


Figure 8. Off Isolation and Crosstalk

#### AC Loadings and Waveforms (Continued)

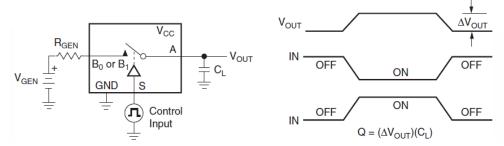


Figure 9. Charge Injection

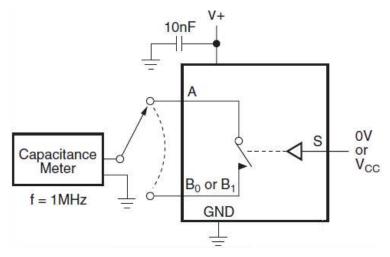


Figure 10. On / Off Capacitance Measurement Setup

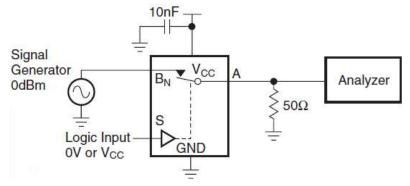


Figure 11. Bandwidth

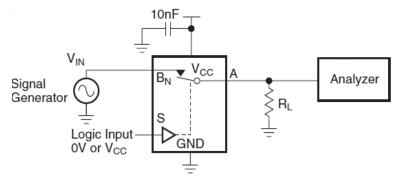
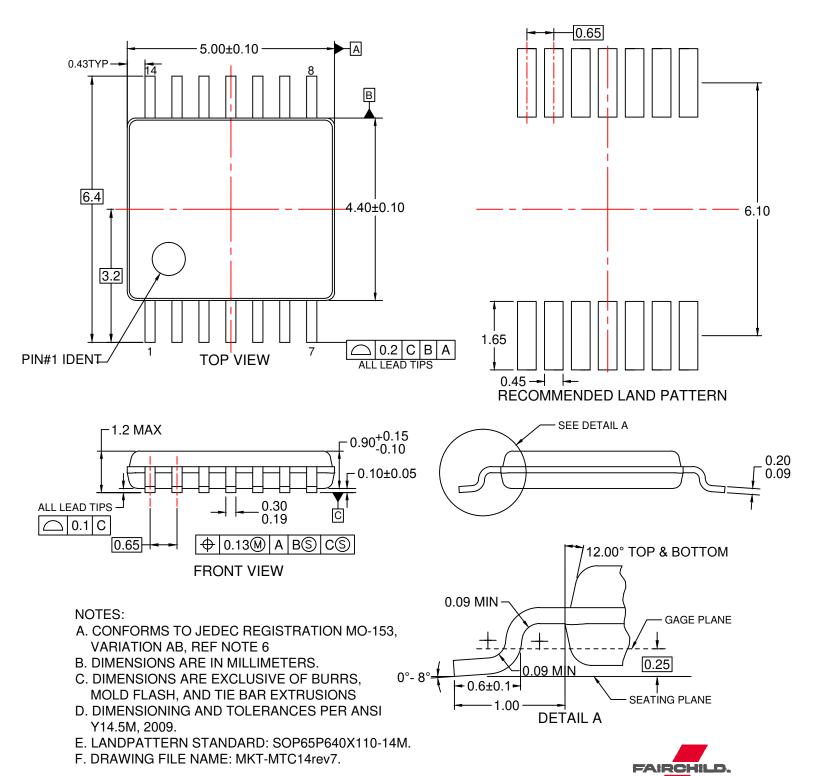
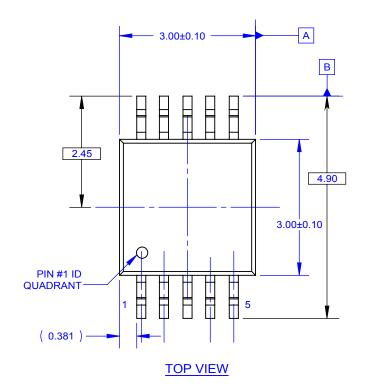


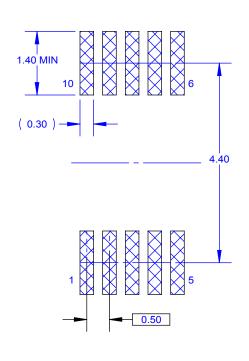
Figure 12. Harmonic Distortion



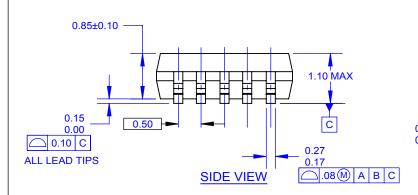
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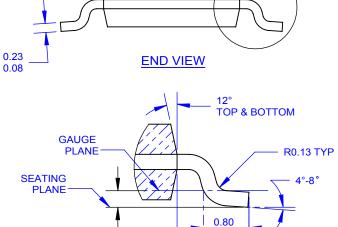
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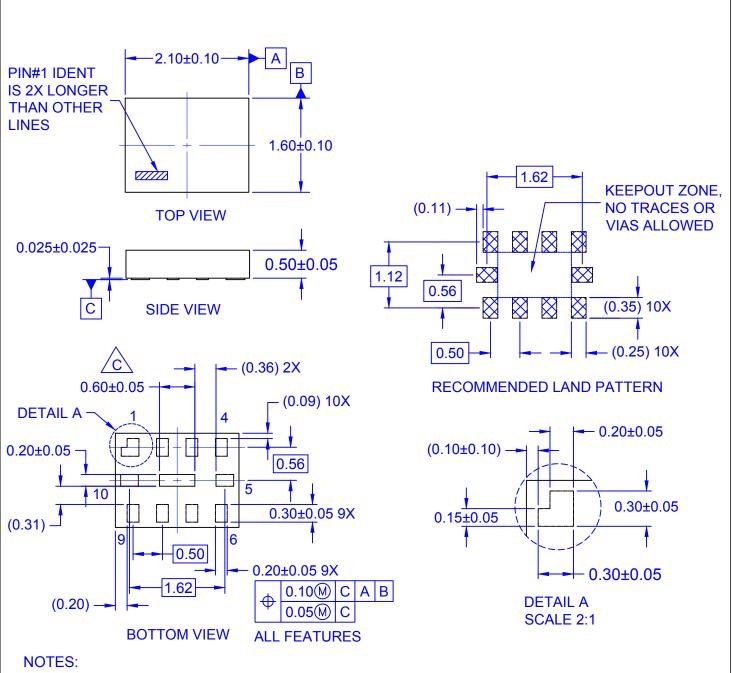
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